

1.2V Drive Nch MOSFET

RUM002N02

●Structure

 Silicon N-channel
 MOSFET

●Applications

Switching

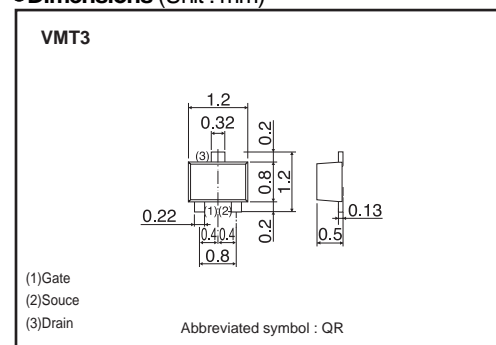
●Features

- 1) Fast switching speed.
- 2) Low voltage drive (1.2V) makes this device ideal for portable equipment.
- 3) Drive circuits can be simple.

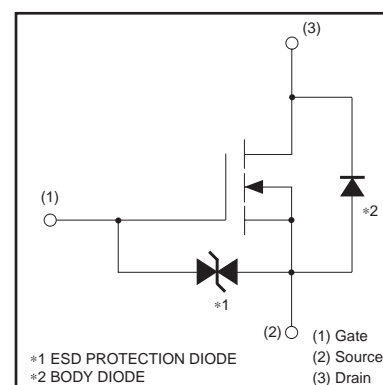
●Packaging specifications

| | | |
|-----------|------------------------------|--------|
| Type | Package | Taping |
| | Code | T2L |
| | Basic ordering unit (pieces) | 8000 |
| RUM002N02 | | ○ |

●Dimensions (Unit : mm)



●Inner circuit



●Absolute maximum ratings (Ta=25°C)

| Parameter | Symbol | Limits | Unit |
|------------------------------|------------|---------------|--------------|
| Drain-source voltage | V_{DS} | 20 | V |
| Gate-source voltage | V_{GS} | ± 8 | V |
| Drain current | Continuous | I_D | ± 200 mA |
| | Pulsed | I_{DP}^{*1} | ± 400 mA |
| Total power dissipation | P_D^{*2} | 150 | mW |
| Channel temperature | T_{ch} | 150 | °C |
| Range of storage temperature | T_{stg} | -55 to +150 | °C |

*1 $P_w \leq 10 \mu s$, Duty cycle $\leq 1\%$

*2 Each terminal mounted on a recommended land

●Thermal resistance

| Parameter | Symbol | Limits | Unit |
|--------------------|--------------------|--------|--------|
| Channel to ambient | $R_{th(ch-a)}^{*}$ | 833 | °C / W |

* Each terminal mounted on a recommended land

●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|-----------------------|------|------|------|------|--|
| Gate-source leakage | I _{GSS} | – | – | ±10 | μA | V _{GS} =±8V, V _{DS} =0V |
| Drain-source breakdown voltage | V _{(BR)DSS} | 20 | – | – | V | I _D =1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | – | – | 1.0 | μA | V _{DS} =20V, V _{GS} =0V |
| Gate threshold voltage | V _{GS(th)} | 0.3 | – | 1.0 | V | V _{DS} =10V, I _D =1mA |
| Static drain-source on-state resistance | R _{DS(on)} * | – | 0.8 | 1.2 | Ω | I _D =200mA, V _{GS} =2.5V |
| | | – | 1.0 | 1.4 | Ω | I _D =200mA, V _{GS} =1.8V |
| | | – | 1.2 | 2.4 | Ω | I _D =40mA, V _{GS} =1.5V |
| | | – | 1.6 | 4.8 | Ω | I _D =20mA, V _{GS} =1.2V |
| Forward transfer admittance | Y _{fs} * | 200 | – | – | mS | V _{DS} =10V, I _D =200mA |
| Input capacitance | C _{iss} | – | 25 | – | pF | V _{DS} =10V |
| Output capacitance | C _{oss} | – | 10 | – | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | – | 10 | – | pF | f=1MHz |
| Turn-on delay time | t _{d(on)} * | – | 5 | – | ns | V _{DD} ≐ 10V, I _D =150mA |
| Rise time | t _r * | – | 10 | – | ns | V _{GS} =4.0V |
| Turn-off delay time | t _{d(off)} * | – | 15 | – | ns | R _L ≐ 67Ω |
| Fall time | t _f * | – | 10 | – | ns | R _G =10Ω |

* Pulsed

●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|-------------------|------|------|------|------|---|
| Forward voltage | V _{SD} * | – | – | 1.2 | V | I _S = 100mA, V _{GS} =0V |

* Pulsed

●Electrical characteristics curves

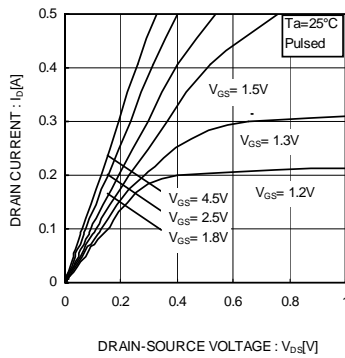


Fig.1 Typical Output Characteristics (I)

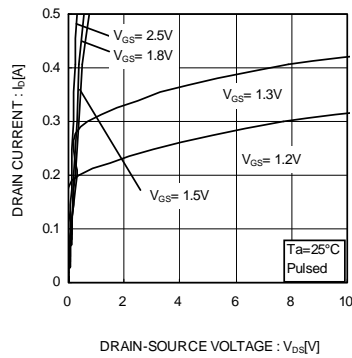


Fig.2 Typical Output Characteristics (II)

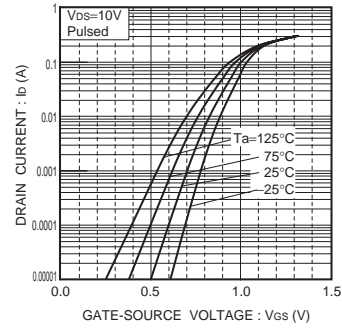


Fig.3 Typical transfer characteristics

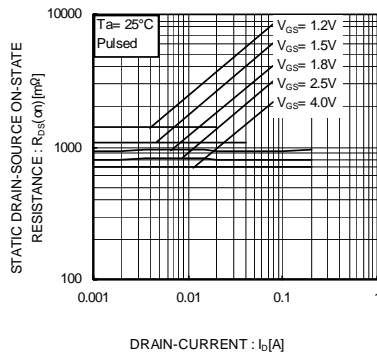


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

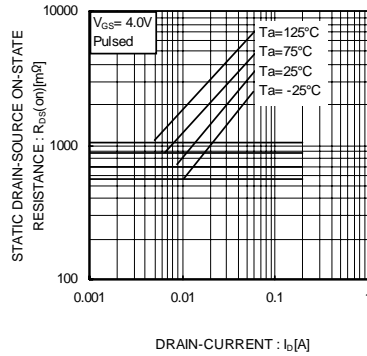


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

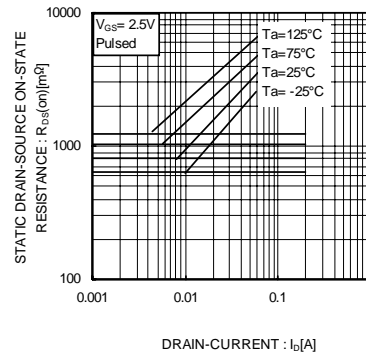


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(II)

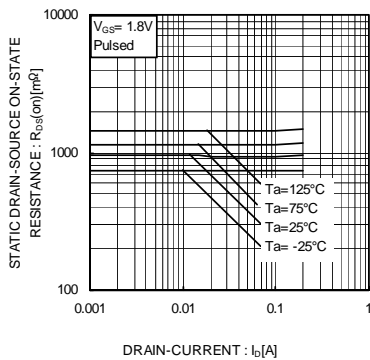


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(III)

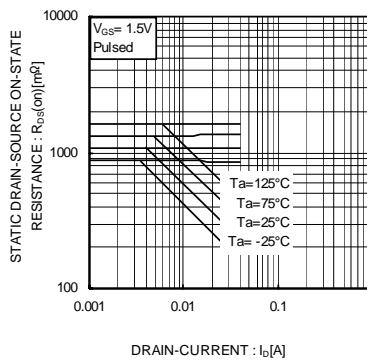


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(IV)

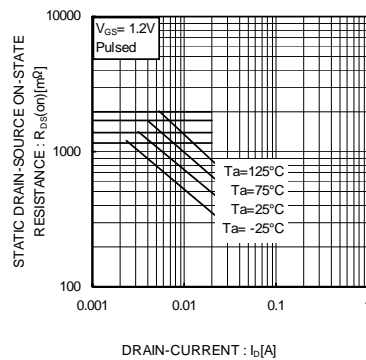


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current(V)

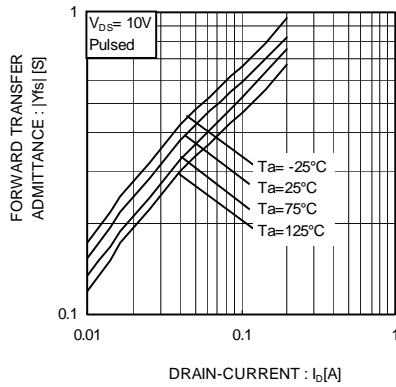


Fig.10 Forward Transfer Admittance vs. Drain Current

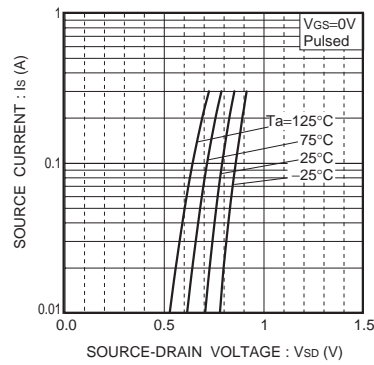


Fig.11 Source current vs. source-drain voltage

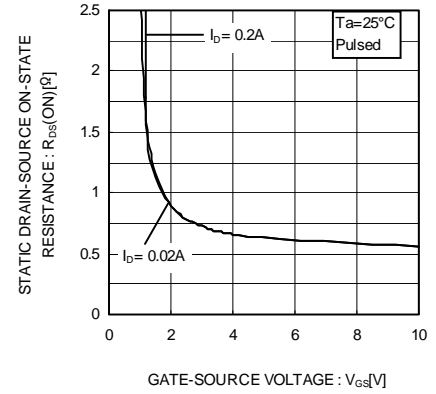


Fig.12 Static Drain-Source On-State Resistance vs. Gate Source Voltage

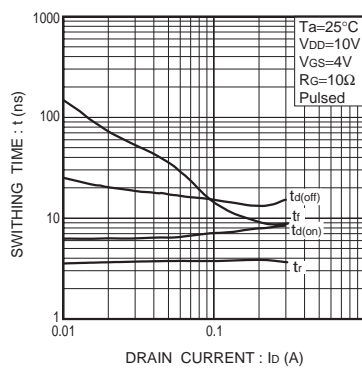


Fig.13 Switching characteristics

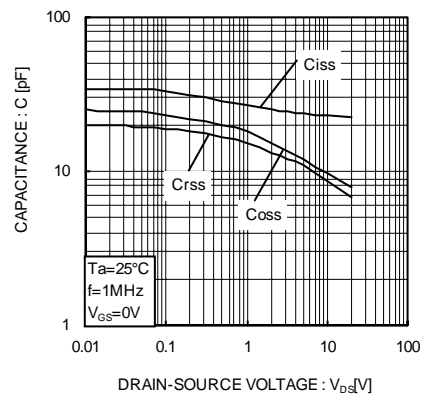


Fig.14 Typical Capacitance vs. Drain-Source Voltage

●Measurement circuit

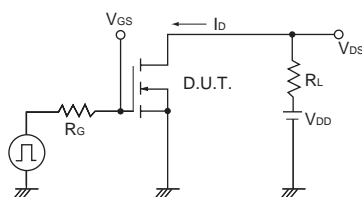


Fig.1-1 Switching time measurement circuit

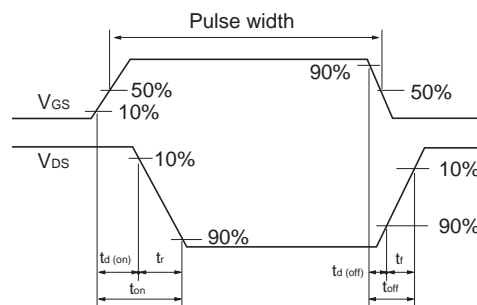


Fig.1-2 Switching waveforms

●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit

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